

FIG. 1a Prior Art

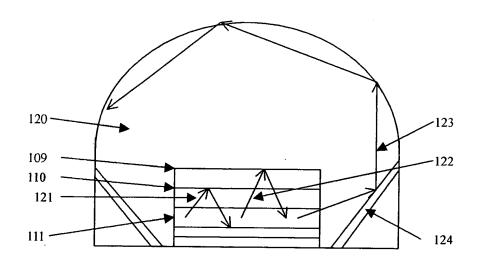


FIG. 1b Prior Art

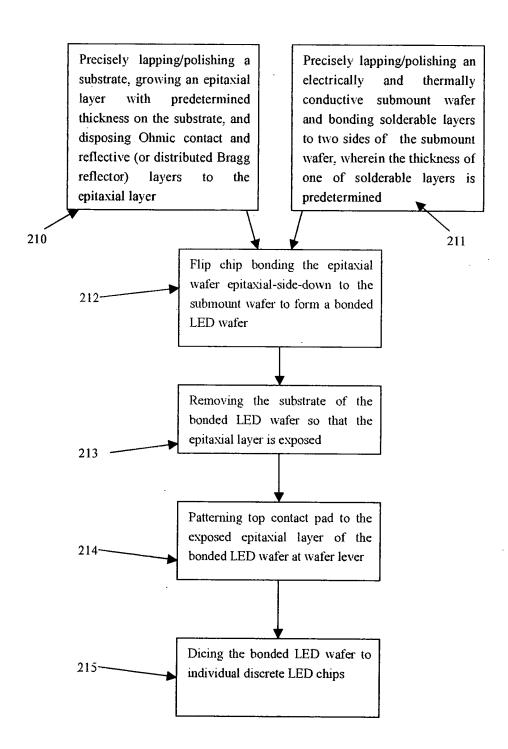


FIG. 2a

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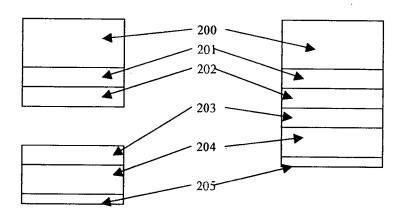


FIG. 2b FIG. 2c

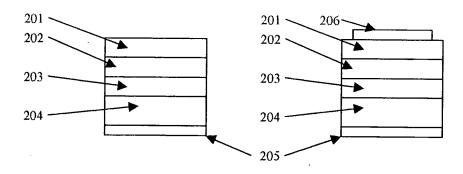


FIG. 2d

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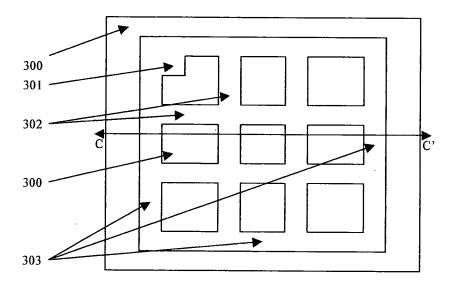
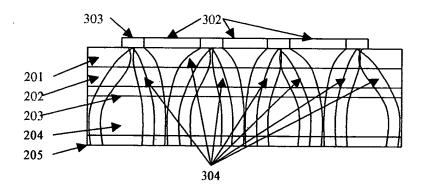


FIG. 3a



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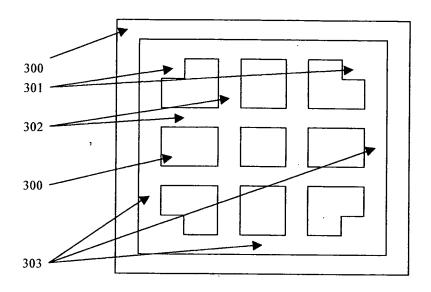


FIG. 3c

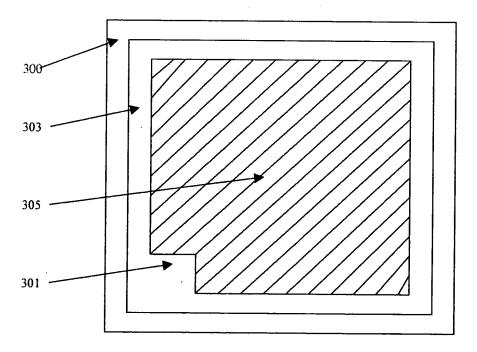


FIG. 3d

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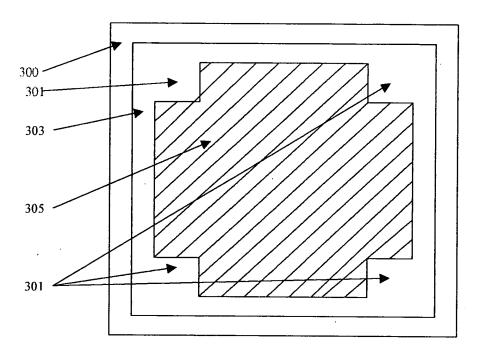


FIG. 3e

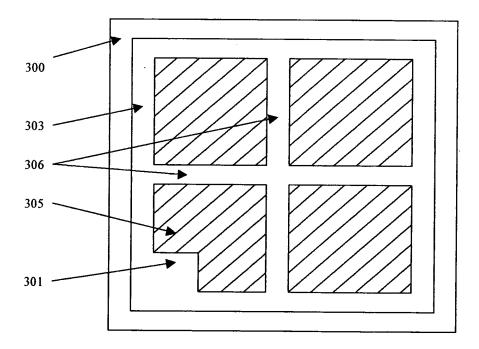


FIG. 3f

New Flip Chip Assemblies and Lamps of High Power GaN LEDs, Wafer Level Flip Chip Package Process, and Method of Fabricating the Same, By Hui Peng (Phone#: 510-794-9953) and Gang Grant Peng

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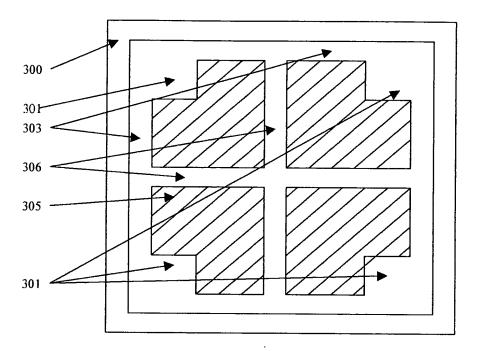


FIG. 3g

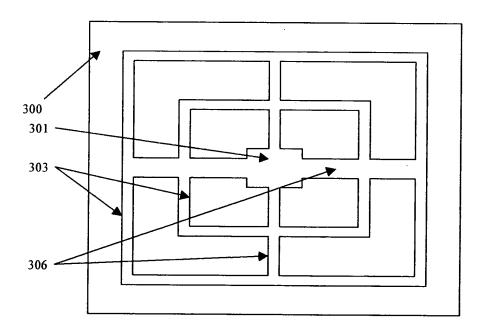
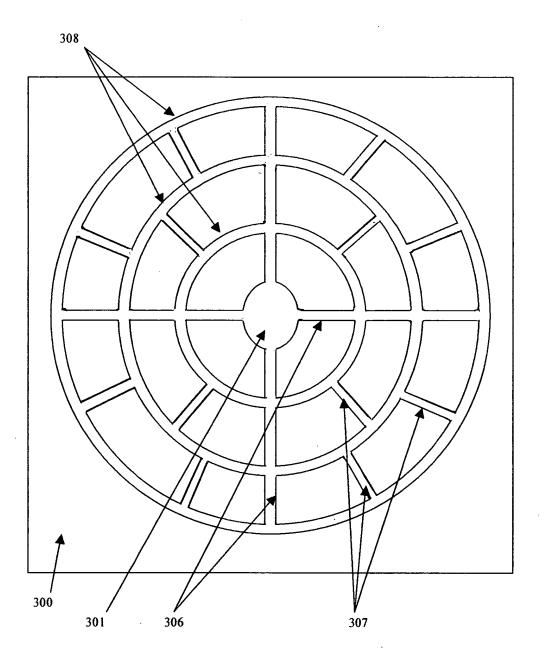


FIG. 3h

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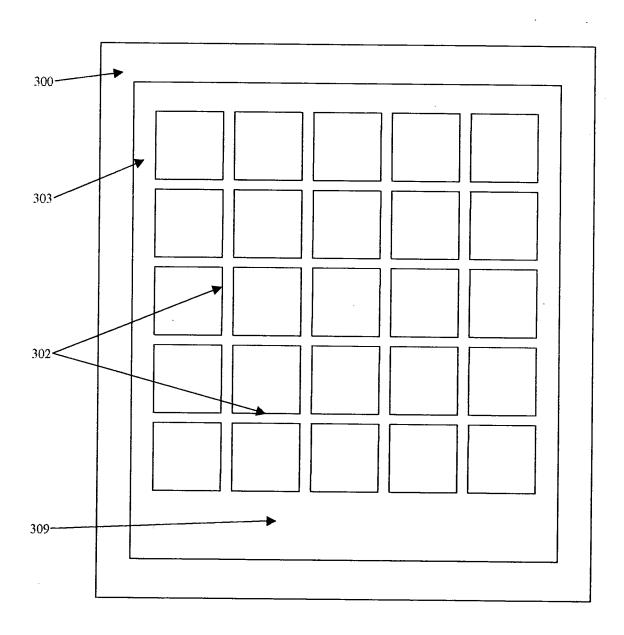


Fig. 3j

New Flip Chip Assemblies and Lamps of High Power GaN LEDs, Wafer Level Flip Chip Package Process, and Method of Fabricating the Same, By Hui Peng (Phone#: 510-794-9953) and Gang Grant Peng

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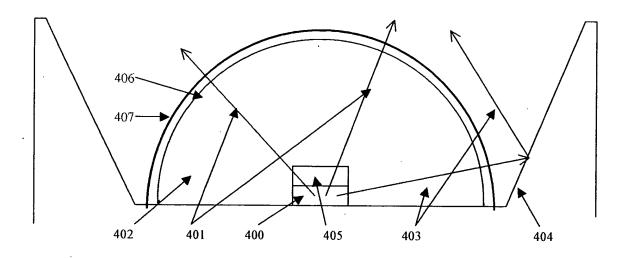


FIG. 4a

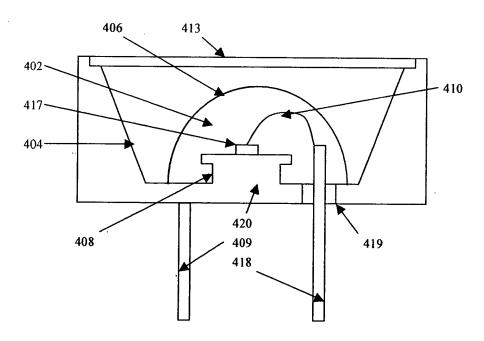


FIG. 4b

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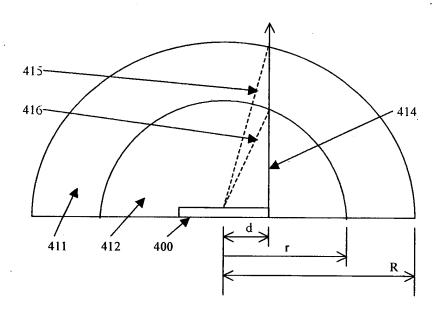


FIG 4c